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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Naoshi ADACHI et al.

Attn: Box PCT

International Application No. PCT/JP2003/013514

I.A. Filing Date: October 22, 2003

Serial No.: Not yet assigned

Filed: July 16, 2004

For: BONDED SOI SUBSTRATE, MANUFACTURING METHOD THEREOF AND  
SEMICONDUCTOR DEVICE

Customer No.: 20374

**PRELIMINARY AMENDMENT**Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

July 16, 2004

Sir:

Prior to calculation of the fee and examination on the merits of the above-identified patent application, please amend the application as follows:

U.S. National Stage of  
PCT/JP2003/013514  
PRELIMINARY AMENDMENT

**PATENT**

**IN THE TITLE:**

Please amend the title of the invention to read as follows:

--~~PASTED~~ BONDED SOI SUBSTRATE, ~~PROCESS FOR PRODUCING THE SAME~~  
MANUFACTURING METHOD THEREOF AND SEMICONDUCTOR DEVICE--